## P-Channel Enhancement Mode Power MOSFET

#### **Description**

The PT Í €Ú€Î uses advanced trench technology and design to provide excellent R<sub>DS(ON)</sub> with low gate charge .This device is well suited for high current load applications.

#### **General Features**

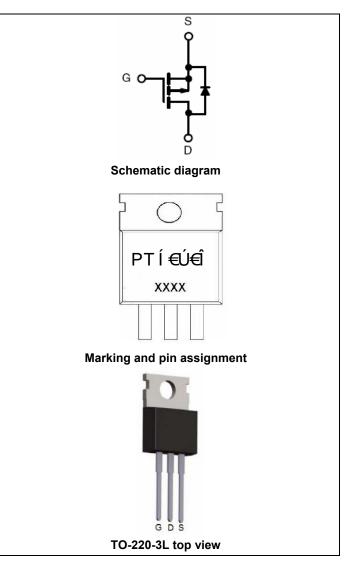
- $V_{DS}$  =-60V, $I_{D}$  =-50A  $R_{DS(ON)}$  <28m $\Omega$  @  $V_{GS}$ =-10V
- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high E<sub>AS</sub>
- Excellent package for good heat dissipation

## **Application**

Load switch

100% UIS TESTED!

100% ΔVds TESTED!



**Package Marking and Ordering Information** 

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
ÁPTÍ€Ú€ÎÁÁÁ	PTÍ€Ú€Î	TO-220-3L	-	-	-

Absolute Maximum Ratings (T<sub>C</sub>=25℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	VDS	-60	V
Gate-Source Voltage	Vgs	±20	V
Drain Current-Continuous	I <sub>D</sub>	-50	Α
Drain Current-Continuous(T <sub>C</sub> =100 °C)	I <sub>D</sub> (100℃)	-35	Α
Pulsed Drain Current	I <sub>DM</sub>	-150	А
Maximum Power Dissipation	P <sub>D</sub>	95	W
Derating factor		0.76	W/°C
Single pulse avalanche energy (Note 5)	E <sub>AS</sub>	722	mJ
Operating Junction and Storage Temperature Range	$T_{J}, T_{STG}$	-55 To 150	$^{\circ}$

### **Thermal Characteristic**

Thermal Resistance, Junction-to-Case(Note 2)	$R_{ heta JC}$	1.31	°C/W	l
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Electrical Characteristics (T<sub>C</sub>=25°C unless otherwise noted)

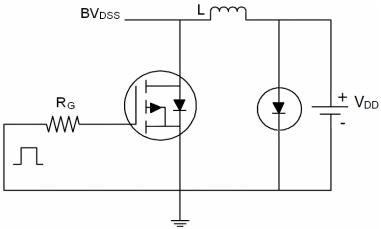
Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics			•			
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =-250μA	′ I <sub>D</sub> =-250μA -60		-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =-60V,V <sub>GS</sub> =0V	-	-	-1	μΑ
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	$V_{GS(th)}$	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =-250μA	-1.2	-1.9	-2.5	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =-10V, I <sub>D</sub> =-20A	-	23	28	mΩ
Forward Transconductance	<b>g</b> FS	V <sub>DS</sub> =-10V,I <sub>D</sub> =-10A	-	25	-	S
Dynamic Characteristics (Note4)						
Input Capacitance	C <sub>lss</sub>	\/ - 25\/\/ -0\/	-	6460	-	PF
Output Capacitance	Coss	$V_{DS}$ =-25V, $V_{GS}$ =0V, F=1.0MHz	-	719	-	PF
Reverse Transfer Capacitance	C <sub>rss</sub>	F-1.UIVITZ	-	535	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t <sub>d(on)</sub>		-	15	-	nS
Turn-on Rise Time	tr	$V_{DD}$ =-30V, $R_L$ =1.5 $\Omega$ ,	-	17	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>	$V_{GS}$ =-10V, $R_{G}$ =3 $\Omega$	-	40	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	45	-	nS
Total Gate Charge	Qg	V = 20 L = 40A	-	75		nC
Gate-Source Charge	$Q_{gs}$	$V_{DS}$ =-30, $I_{D}$ =-10A, $V_{GS}$ =-10V	-	16		nC
Gate-Drain Charge	$Q_{gd}$	VGS10V	-	19		nC
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage (Note 3)	V <sub>SD</sub>	V <sub>GS</sub> =0V,I <sub>S</sub> =-10A	-		-1.2	V
Diode Forward Current (Note 2)	Is		-	-	-20	Α
Reverse Recovery Time	t <sub>rr</sub>	TJ = 25°C, IF =- 10A	-	50		nS
Reverse Recovery Charge	Qrr	di/dt = -100A/µs(Note3)	-	59		nC
Forward Turn-On Time	t <sub>on</sub>	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				

#### Notes:

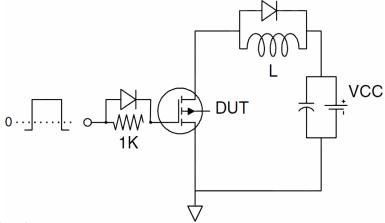
- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- **2.** Surface Mounted on FR4 Board,  $t \le 10$  sec.
- **3.** Pulse Test: Pulse Width ≤  $300\mu$ s, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to production
- **5.** E<sub>AS</sub> condition: Tj=25  $^{\circ}\text{C}$  ,V<sub>DD</sub>=-20V,V<sub>G</sub>=-10V,L=1mH,Rg=25 $\Omega$ ,I<sub>AS</sub>=38A

### **Test Circuit**

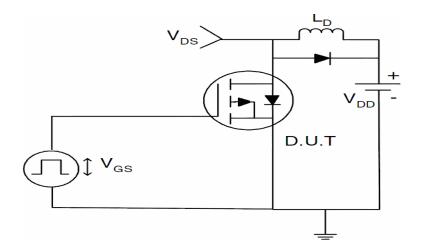
## 1) E<sub>AS</sub> Test Circuit



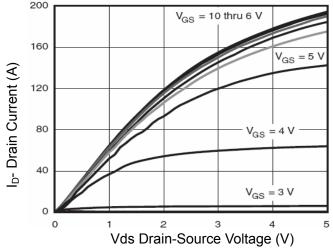
## 2) Gate Charge Test Circuit



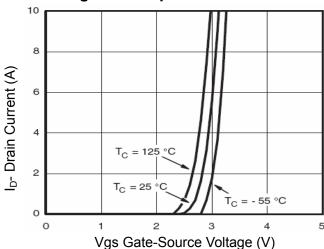
## 3) Switch Time Test Circuit



# Typical Electrical and Thermal Characteristics (Curves)



**Figure 1 Output Characteristics** 



**Figure 2 Transfer Characteristics** 

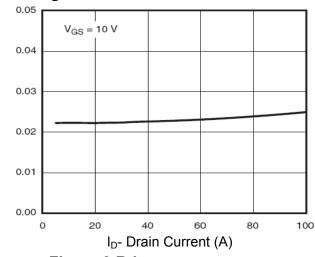
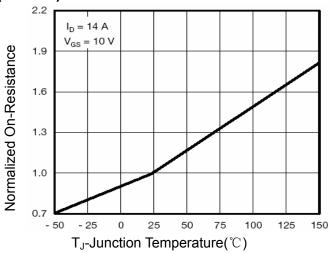


Figure 3 Rdson- Drain Current



**Figure 4 Rdson-Junction Temperature** 

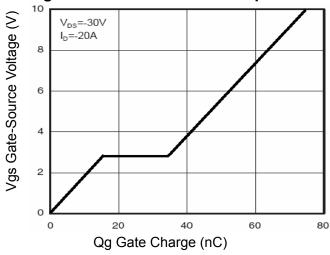


Figure 5 Gate Charge

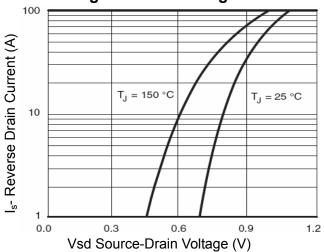


Figure 6 Source- Drain Diode Forward

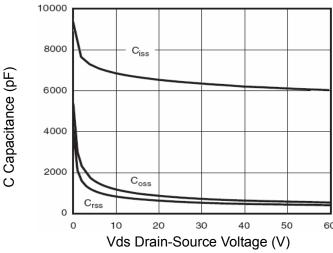


Figure 7 Capacitance vs Vds

1000

Limited by  $R_{DS(on)}^*$ 100  $\mu_{S}$ 

**Figure 8 Safe Operation Area** 

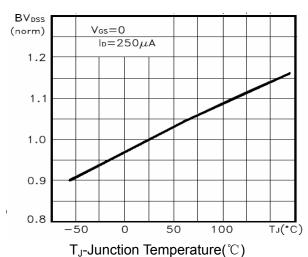


Figure 9 BV<sub>DSS</sub> vs Junction Temperature

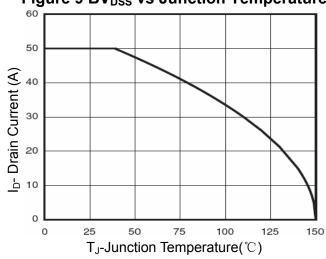


Figure 10 ID Current Derating vs Junction Temperature

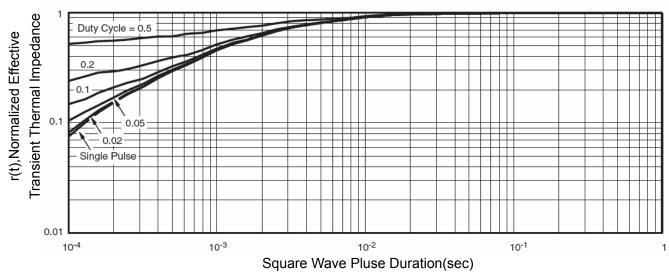
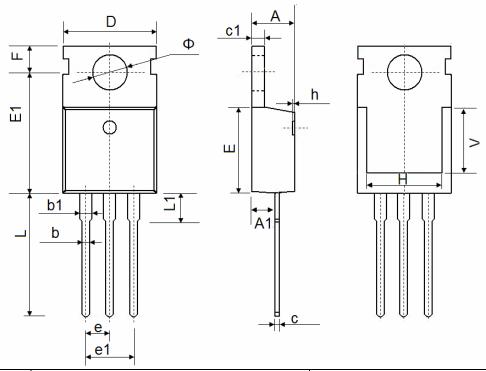


Figure 11 Normalized Maximum Transient Thermal Impedance

## **TO-220-3L Package Information**



Cumbal	Dimensions	In Millimeters	Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
А	4.400	4.600	0.173	0.181	
A1	2.250	2.550	0.089	0.100	
b	0.710	0.910	0.028	0.036	
b1	1.170	1.370	0.046	0.054	
С	0.330	0.650	0.013	0.026	
c1	1.200	1.400	0.047	0.055	
D	9.910	10.250	0.390	0.404	
Е	8.9500	9.750	0.352	0.384	
E1	12.650	12.950	0.498	0.510	
е	2.54	0 TYP.	0.100 TYP.		
e1	4.980	5.180	0.196	0.204	
F	2.650	2.950	0.104	0.116	
Н	7.900	8.100	0.311	0.319	
h	0.000	0.300	0.000	0.012	
L	12.900	13.400	0.508	0.528	
L1	2.850	3.250	0.112	0.128	
V	7.50	0 REF.	REF. 0.295 REF.		
Ф	3.400	3.800	0.134	0.150	

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